



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/038,264  
Applicant : Seungbae Park et al.  
Filed : January 3, 2002  
TC/A.U. : 3679  
Examiner : Ernesto Garcia

18/Amendment con  
CP  
10-27-03

Docket No. : EN999048D  
Title : SOLDER INTERCONNECT TECHNIQUES  
Customer No. : 36458

SUPPLEMENTAL AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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S I R:

In response to the Office action of October 3, 2003,  
please amend the above-identified application as indicated.  
This amendment replaces in its entirety the amendment filed on  
September 8, 2003.

**Amendments to the Specification** begin on page 2 of this  
paper.

**Amendments to the Claims** begin on page 3 of this paper.

**Amendments to the Drawings** begin on page 6 of this paper  
and include both an attached replacement sheet and an  
annotated sheet showing changes.

**Remarks/Arguments** begin on page 7 of this paper.

An **Appendix** including amended drawing figures is attached  
following page 9 of this paper.

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